

26 August 2020

TENDER NO.: **NITD/SERB/AG/ME/LMM/2020-21** dated 17 August 2020

Pre-bid Conference Meeting held on 26.08.2020 at 1500Hrs through google meet.

The followings are resolved after the pre-bid conference meeting and discussions within the DPC.

Few minor modifications and typo error corrections have been made in the Technical Specifications of the Laser Marking Machine, listed below:

Sl. No.	Point Number and Page Number	Requirements/Descriptions as given in the bid	<i>Requirements/Descriptions Should be read as</i>
1.	Page Number 6 I. Technical Specifications, Point Number 13 Materials that can be processed	Metal, Plastic, Semi-Conductor	<i>Metal, Hard Plastics, Semi-Conductors (Silicon wafers)</i>
2.	Page Number 16 Annexure I: Compliance Sheet for Laser Marking Machine, Point Number 3, Maximum Working Area	160 X 160 mm	<i>100 X 100 mm or higher</i>
3.	Page Number 16 Annexure I: Compliance Sheet for Laser Marking Machine , Point Number 4, Peak Emission Wavelength	1064 +/- 10 n or better for fabricating micron scale features	<i>1064 +/- 10 nm or better for fabricating micron scale features</i>
4.	Page Number 16 Annexure I: Compliance Sheet for Laser Marking Machine, Point Number 13, Materials that can be processed	Metal, Plastic, Semi-Conductor	<i>Metal, Hard Plastics, Semi-Conductors (Silicon wafers)</i>

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